SCOPE:

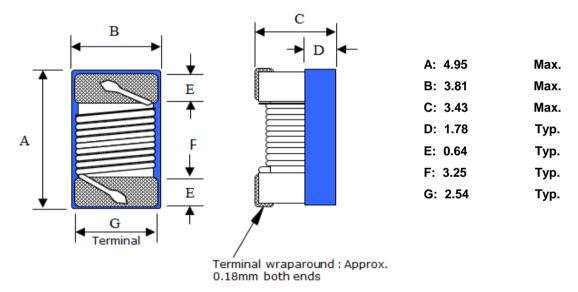
This specification applies to the Pb Free Ceramic Chip Inductors for MWCS-453226-SERIES

PRODUCT INDENTIFICATION

MWCS - 453226 - 22N J

- ① ② ③ ④
- ① Product Code
- 2 Dimensions Code
- **3 Inductance Code**
- **4** Tolerance Code

(1) SHAPES AND DIMENSIONS(mm)



(2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

TEST INSTRUMENTS

L,Q: HP 4291B IMPEDANCE ANALYZER (or equivalent)
SRF: ENA E5071B NETWORK ANALYZER (or equivalent)

RDC: CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

(3) CHARACTERISTICS

(3)-1 Operate temperature range $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (Including self temp. rise)

(3)-2 Storage temperature range -40° C $\sim +125^{\circ}$ C



TABLE 1

MAGLAYERS	Inductance	Percent	L/Q Freq.	Quality	SRF	DCR	Irms
PT/NO.	L(uH)	Tolerance	(MHz)	Min.	(MHz)Min.	(Ω) Max.	(mA) Typ.
MWCS-453226-1R0□	1.0	J,K	7.9/50	60	310	1.20	480
MWCS-453226-1R2□	1.2	J,K	7.9/50	62	230	1.20	480
MWCS-453226-1R5□	1.5	G,J,K	7.9/50	65	210	1.60	430
MWCS-453226-1R8□	1.8	J,K	7.9/50	68	190	2.00	380
MWCS-453226-2R2□	2.2	G,J,K	7.9/50	63	170	2.20	340
MWCS-453226-2R7□	2.7	G,J,K	7.9/50	60	160	3.20	300
MWCS-453226-3R3□	3.3	G,J,K	7.9/50	60	145	3.80	270
MWCS-453226-3R9□	3.9	G,J,K	7.9/50	61	130	5.00	240
MWCS-453226-4R7□	4.7	J,K	7.9/50	60	115	5.40	230
MWCS-453226-5R6□	5.6	J,K	7.9/50	42	100	5.70	220
MWCS-453226-6R8□	6.8	J,K	7.9/50	32	90	6.60	210
MWCS-453226-8R2□	8.2	G,J,K	7.9/50	35	80	7.00	200
MWCS-453226-100□	10	J,K	7.9/50	27	70	7.70	190
MWCS-453226-120	12	J,K	2.5/10	34	58	8.70	180
MWCS-453226-150	15	G,J,K	2.5/10	32	48	9.60	170
MWCS-453226-180	18	J,K	2.5/10	28	36	10.50	160
MWCS-453226-220	22	G,J,K	2.5/10	28	34	11.50	155
MWCS-453226-270	27	J,K	2.5/10	28	30	12.50	150
MWCS-453226-330	33	G,J,K	2.5/10	20	20	13.50	145

- % 1. Please specify the inductance tolerance, G(±2%),J(±5%),K(±10%)
 - 2. L/Q Test OSC @200mV.
 - 2. Irms for a 15 $\!\!\!\!\!^{\,\circ}_{\,\circ}$ temperature rise from 25 $\!\!\!\!\!^{\,\circ}_{\,\circ}$ ambient .

(4) RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS			
Solder ability	The electrodes shall be at least 90% covered	Refer to J-STD-002			
	with new solder coating	Pre-heating: 150℃, 1min			
		Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)			
		Solder Temperature: 245±5℃ (Pb-Free) Immersion Time: 4±1sec			
Resistance to	There shall be no damage or problems.	Refer to MIL-STD-202 Method 210			
Soldering heat	Inductance change shall be within ±10%.	Temperature profile of reflow soldering			
(reflow soldering)	Q change:within±30% of initial value	Temperature			
		Ramp up: Ramp down: 3°C/sec. max. 6°C/sec. max.			
		260°C			
		217°C			
		160°C Soldering			
		260°C ±3 °C 10 - 30 sec.			
		25°C ← Preheat → ← Liquidus → Time			
		150-200°C >217°C 60-120 sec. 60-150 sec.			
		The specimen shall be passed through the reflow oven			
		with the condition shown in the above profile for 1 time.			
		The specimen shall be stored at standard atmospheric			
		eric conditions for 1 hour, after which the measurement shall be made.			
Terminal strength	The terminal electrode and the ferrite must	Refer to AEC-Q200-006			
not damaged.		Test device shall be soldered on the substrate			
		Force 0.5lbs for 60±1 seconds for 0201 series			
		Force 1lbs for 60±1 seconds for 0402 series			
		Force 2lbs for 60±1 seconds for 0603 series			
		Force 1.8Kg for 60±1 seconds for the other series.			
Board Flex	The terminal electrode and the ferrite must	Refer to AEC-Q200-005			
Board Fiex	not damaged.	Test device shall be soldered on the substrate			
	not damaged.	Substrate Dimension: 100x40x1.6mm			
		Deflection: 2.0mm			
		Keeping Time: 60sec			
		reeping Time. obset			
		45 45			
	Annearance No damage (for microscope				
High	Appearance:No damage (for microscope	Refer to MIL-STD-202 Method 108			
temperature	of CASTOR MZ-420X)Inductance change shall	Temperature: 125±3℃ / Relative Humidity: 0% Time: 100hrs			
resistance	Inductance change shall be within ±10%.				
(Storage)	Q change:within±30% of initial value	Measured after exposure in the room condition for 24hrs			
Diseased House Labber	Annana Markana (f	Defeate MIL OTD 200 Method 400			
Biased Humidity	Appearance:No damage (for microscope	Refer to MIL-STD-202 Method 103			
	of CASTOR MZ-420X)Inductance change shall	Temperature: 85±2℃			
	Inductance change shall be within ±10%.	Relative Humidity:85% / Time: 100hrs			
	Q change:within±30% of initial value	Measured after exposure in the room condition for 24hrs			



(4) RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS		
Thermal shock	Appearance:No damage (for microscope	Refer to JESD Method JA-104		
	of CASTOR MZ-420X)Inductance change shall	Total cycles: 100 cycles		
	Inductance change shall be within ±10%.	Temperature Cycling Test Conditions : -40 to +125 ℃		
	Q change:within±30% of initial value	-40 ℃ Soak Mode Condition: 30 minutes		
		125 ℃ Soak Mode Condition : 30 minutes		
		Measured after exposure in the room condition for 24hrs		
Low	There shall be no damage or problems.	After the samples shall be soldered onto the test		
temperature	Inductance change shall be within ±10%.	circuit board,the test shall be done.		
storage	Q change:within±30% of initial value	Measurement : After placing for 24 hours min.		
		Temperature : -40±2℃		
		Testing time : 100 hours		
Vibration	There shall be no damage or problems.	Refer MIL-STD-202 Method 204		
	Inductance change shall be within ±10%.	Vibration waveform: Sine waveform		
	Q change:within±30% of initial value	Vibration frequency: 10Hz~2000Hz		
		Vibration acceleration: 5g		
		Sweep rate: 0.764386otcave/minute		
		Duration of test: 12 cycles each of 3 orientations,		
		20 minutes for each cycle		
		Vibration axes: X, Y & Z		
Resistance to Solvent	There must be no change in	Refer to MIL-STD-202 Method 215		
	appearance or obliteration of	Inductors must withstand 6 mimutes of alcohol or water.		
	marking			
Operational Life	No apparent damage	Refer to MIL-STD-202 Method 108		
	Inductance change shall be within ±10%.	Temperature: 125±3℃		
		Applied Current : Rated Current		
		Time: 100hrs		
		Measured after exposure in the room condition for 24hrs		

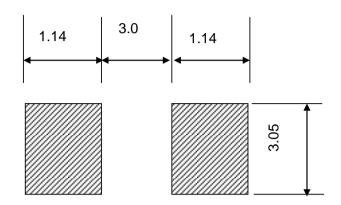


(5) RECOMMENDED SOLDERING CONDITIONS

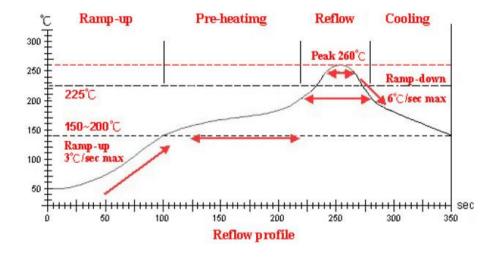
(Please use this product by reflow soldering)

(5)-1 RECOMMENDED FOOTPRINT

Unit: mm



(5)-2 RECOMMENED REFLOW PATTERN



Lead-Free(LF) Refer to J-STD-020C

Item	Ramp-up	Pre-heating	Reflow	Peak Temp.	Cooling
Temp. scope	R.T.~150℃	150℃~200℃	225 ℃	260±5 ℃	Peak Temp.~150°C
Time result	_	60~180 Sec.	20~60 Sec.	5~10 Sec.	_

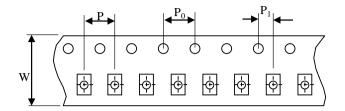
NOTE:

- 1. Re-flow possibile times:with in 2 times
- 2. Nitrogen adopted is recommended while in re-flow



(6) PACKAGING

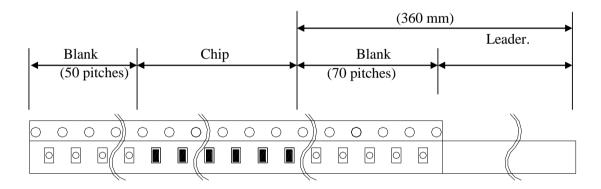
(6)-1 CARRIER TAPE DIMENSIONS (mm)



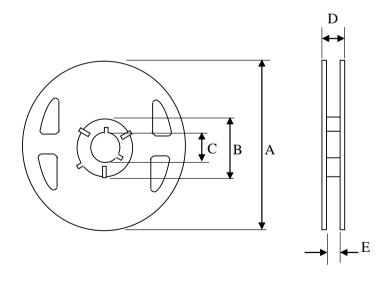
W: 12.0 mm
P: 8.0 mm
P0: 4.0 mm
P1: 2.0 mm

(6)-2 TAPING DIMENSIONS (mm)

There shall not continuation more than two vacancies of the product.



(6)-3 REEL DIMENSIONS



A: 178 mm
B: 60.0 mm
C: 13.0 mm
D: 12.0 mm
E: 9.0 mm

(6)-4 COVER TAPE PEEL STRENGTH

The force for tearing off cover tape is 10 to 100 grams in the arrow direction



(6)-5 QUANTITY

600 pcs/Reel

(6)-6 The products are packaged so that no damage will be sustained.

(7) ATTENTION IN CASE OF USING

In case of using product ,please avoid following matters:

Splashing water or salt water

Dew condenses

Toxic gas (Hydrogen sulfide, Sulfurous acid ,Chlorine, Ammonia)

Vibrations or shocks which exceed the specified condition

Please be careful for the stress to this product by board flexure or something after the mounting.

Please note that the contents may change without any prior notice due to reasons such as upgrading.

